

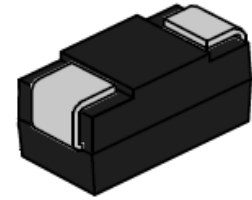


CP1101SB/CP1301SB TSS

Rev.1.1

DESCRIPTION:

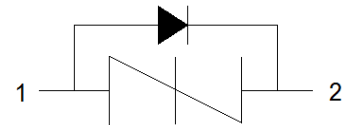
CP1101SB/CP1301SB are a type of uni-directional semiconduct component. They are designed to protect baseband equipment from damaging overvoltage transients. such as modems, telephones, line cards, answering machines, FAX machines, T1/E1, xDSL and more.



SMB

FEATURES:

- ✧ Excellent capability of absorbing transient surge.
- ✧ Quick response to surge voltage (ns Level).
- ✧ Eliminates overvoltage caused by fast rising transients.
- ✧ Moisture sensitivity level: Level 1.
- ✧ Non degenerative.



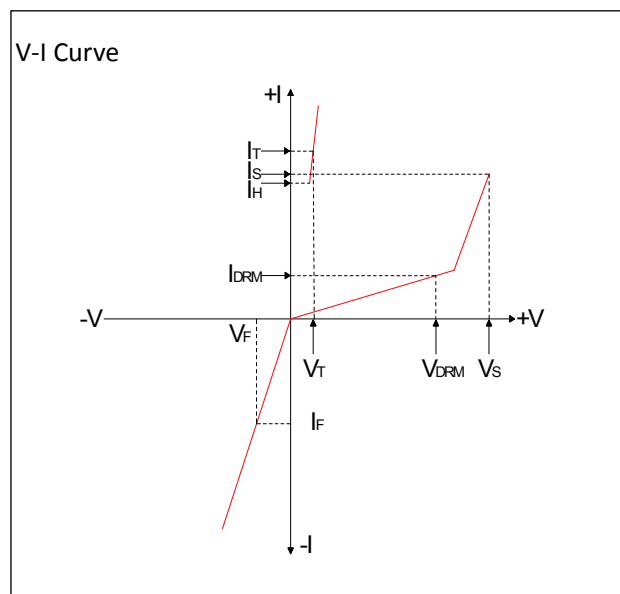
Symbol

ABSOLUTE MAXIMUM RATINGS (T_A=25°C, RH=45%-75%, unless otherwise noted)

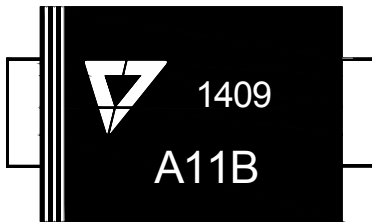
Parameter	Symbol	Value	Unit
Storage temperature range	T _{STG}	-60 to +150	°C
Operating junction temperature range	T _J	-40 to +125	°C
Repetitive peak pulse current@10/1000µs	I _{PP}	80	A

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Symbol	Parameter
V _{DRM}	Peak off-state voltage
I _{DRM}	Off-state current
V _S	Switching voltage
I _S	Switching current
V _T	On-state voltage
I _T	On-state current
I _H	Holding current
C _O	Off-state capacitance
V _F	Forward voltage



MARKING



A11B : Device Marking Code
1409: In ninth week, 2014

ELECTRICAL CHARACTERISTICS (T_A=25°C, continued)

Part Number	I _{DRM} @V _{DRM} PIN2-1		V _S ^① @I _S PIN2-1		V _T @ I _T PIN2-1		I _H PIN2-1	V _F @I _F =10mA PIN1-2	C _O ^② PIN2-1	Marking
	μA	V	V	mA	V	A	mA	V	pF	
	max		max	max	max	max	min	max	max	
CP1101SB	1	95	130	800	4	2.2	100	1.0	70	A11B
CP1301SB	1	115	140	800	4	2.2	100	1.0	70	A13B

① V_S is measured at 100KV/s

② Off-state capacitance is measured in V_{DC}=2V, V_{RMS}=1V, f=1MHz

SURGE RATINGS

Series	I _{PP} (A) min			
	2×10μs	8×20μs	10×360μs	10×1000μs
B	250	250	125	80

ORDERING INFORMATION

<p>CP</p> <p>Series code P: SIDACTor</p>	<p>110</p> <p>Median voltage</p>	<p>1</p> <p>0: Bi-direction 1: Uni-direction</p>	<p>S</p> <p>Package type:SMB</p>	<p>B</p> <p>Surge ratings:4KV(10/700μs)</p>
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SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see FIG.2)
Pre Heat	-Temperature Min ($T_{S(min)}$)	+150°C
	-Temperature Max($T_{S(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C

FIG.1: tr × td pulse waveform

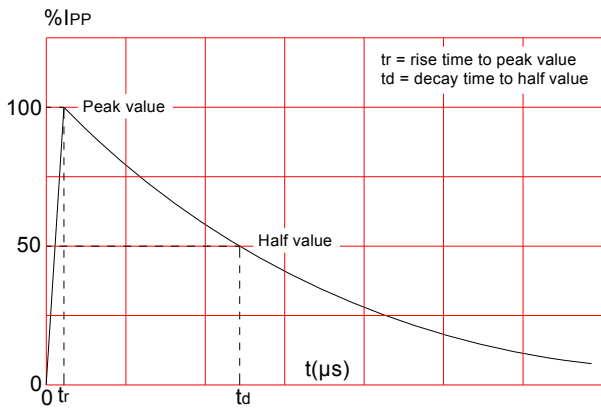


FIG.2: Reflow condition

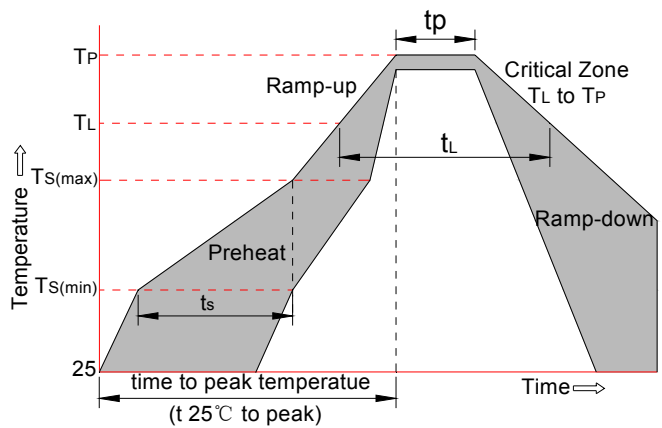


FIG.3: Normalized V_s change vs. junction temperature

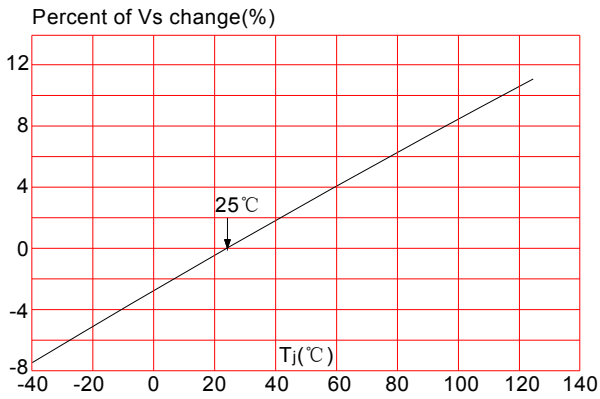
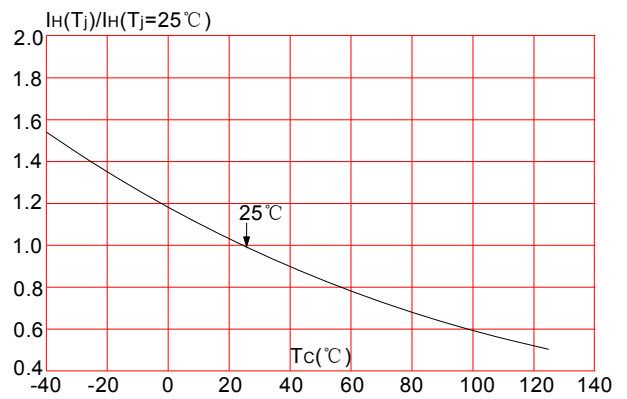
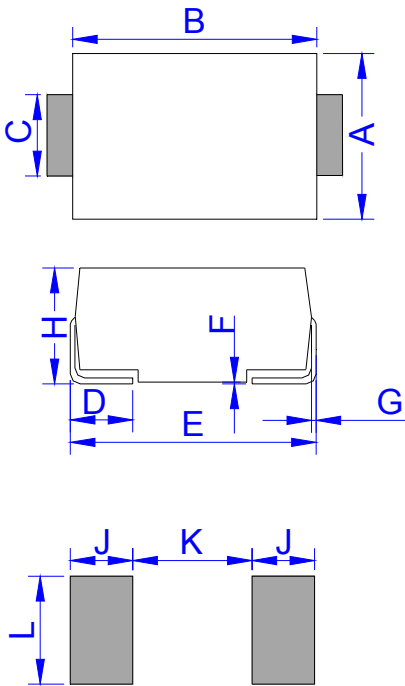


FIG.4: Normalized DC holding current vs. case temperature



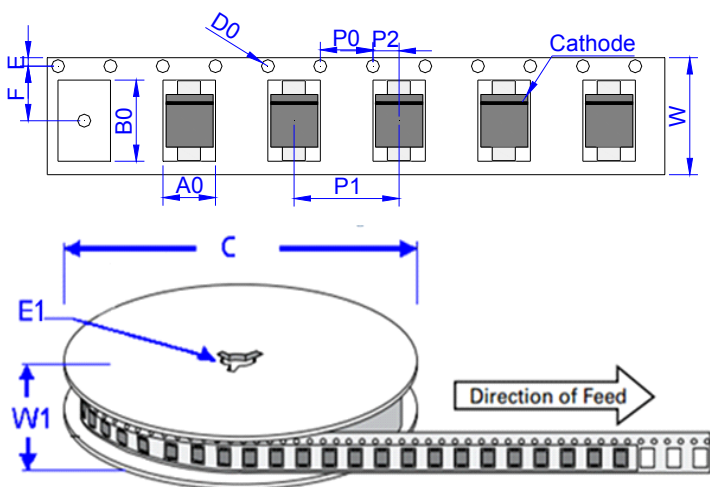
PACKAGE MECHANICAL DATA



DO-214AA (SMB)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.30	3.94	0.130	0.155
B	4.30	4.80	0.169	0.189
C	1.90	2.20	0.075	0.087
D	0.95	1.52	0.037	0.060
E	5.20	5.60	0.205	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.10	2.40	0.083	0.094
J	2.20		0.087	
K		2.60		0.102
L	2.30		0.091	

TAPE AND REEL SPECIFICATION-SMB



Ref.	Dimensions	
	Millimeters	Inches
A0	3.76 ± 0.3	0.148 ± 0.012
B0	5.69± 0.3	0.224 ± 0.012
C	330.0	13.0
D0	1.55 ± 0.1	0.061 ± 0.004
E	1.75 ± 0.2	0.069 ± 0.008
E1	13.3 ± 0.3	0.524± 0.012
F	5.5 ± 0.2	0.217 ± 0.008
P0	4.00 ± 0.2	0.157 ± 0.008
P1	8.00 ± 0.2	0.3145 ± 0.008
P2	2.00 ± 0.2	0.079 ± 0.008
W	12.0± 0.2	0.472 ± 0.008
W1	15.7 ± 2.0	0.618 ± 0.079


OUTLINE	UNIT WEIGHT (g/PCS) typ.	REEL (PCS)	PER CARTON (PCS)	REEL DIAMETERS (mm)
TAPING	0.098	3,000	48,000	330

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